# Plaskon NXG-1LAR

### Epoxy; Epoxide

#### Cookson Electronics - Semiconductor Products

#### Message:

This material is an epoxy molding compound for high temperature, lead-free reflow in low alpha applications. It is designed to withstand more demanding requirements in moisture performance, occasioned by the higher IR reflow temperatures required for processing lead-free packages. It is a highly filled, hybrid resin developed to pass JEDEC Level 2A at 260°C IR reflow temperature. It is a "green" compound with no halogens and a lower Tg than multifunctional materials.

General Information			
Features	Semi-conductive		
	Low hygroscopicity		
	Fast curing		
	Good formability		
	Halogen-free		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	2.00	g/cm³	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	2.45	MPa	ASTM D790
260°C	0.0686	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0123	MPa	ASTM D790
260°C	8.14E-4	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	150	°C	ASTM E1356
CLTE - Flow	9.0E-6	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Flammability	Nominal Value		Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			

Recommended Storage Temperature: <5°CLife @ 5°C: 6 monthsLife @ 22°C: 2 daysLife @ 35°C: 0.5 daysSpiral Flow, 175°C, 1000 psi: 132 cmShimadzu Viscosity, 175°C, 1000 psi: 55 poiseRam Follower Gel Time, 175°C, 1000 psi: 18 secAsh Content: 88.6 %Hydrolyzable Halides: <1 ppmAlpha Particle Count: <0.002 counts/cm<sup>2</sup>/hrMoisture Absorption, 85°C/85%RH, 168 hrs: 0.275%Cull Hot Hardness, Shore D: 75All test specimens are transfer molded and post cured for 4 hours at 175°C

Linear Thermal Expansion, Alpha 1: 9 cm<sup>-6/cm</sup>°C

Linear Thermal Expansion, Alpha 2: 35 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding: Molding Temperature: 165 to 185°C Molding Pressure: 1000 psi In Mold Cure Time: 50 to 100 sec Post Mold Cure Time, 175°C: 0 to 2 hr

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Recommended distributors for this material

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